LM555 or SN74AUP3G14

Oscillator

SN74AUP1G19

H Bridge

Rectifier

Turn-off

CSD19537Q3

Power MOSFETs

ON

SR Latch

OFF

SN74AUP1G74

A

EN
Engineer: Jarrod Krebs  
Contact:  
File: TIDA-00751 SSR_OSC+Relay.SchDoc  
Size: B  
Mod. Date: 12/10/2015  

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You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Nexperia Inc.). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

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Label Table

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>01</td>
<td>ChangeMe!</td>
</tr>
<tr>
<td>02</td>
<td>ChangeMe!</td>
</tr>
</tbody>
</table>

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Assembly Notes:

1. These assemblies are ESD sensitive, ESD precautions shall be observed.
2. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
3. These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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